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ABSTRACT

The present invention provides a method for mounting a semiconductor element to a circuit board and a semiconductor device whereby connection reliability and connection strength in bonding of the semiconductor element and circuit board are enhanced and a connection resistance value is stabilized low. An insulating adhesive (107) is applied to an opposite face (101a) of a circuit board (101). The circuit board is then connected with a semiconductor element (103) by a conductive adhesive (106) and the insulating adhesive which are interposed between an electrode (102) on the circuit board and the projecting electrode and set in the same process. The circuit board and semiconductor element are connected by the insulating adhesive in addition to the conductive adhesive, so that connection reliability and connection strength are high and a connection resistance value is stabilized low.